



PCN: TongFu Microelectronics Co., Ltd (TFME) as a Subcontractor for the Assembly of 32L QFN package

Zilog, Inc.
1590 Buckeye Drive
Milpitas, CA 95035-7418

April 12, 2021

Subject: TongFu Microelectronics Co., Ltd (TFME) as a Subcontractor for the Assembly of 32L QFN package.

Dear Valued Customer and/or Distributor:

We would like to inform you that we have qualified TongFu Microelectronics Co., Ltd (TFME) for the assembly of the 32L QFN package using our standard qualification process (please see the attached qualification data).

TongFu Microelectronics Co., Ltd (TFME) is a previously existing qualified package Subcontractors.

Should you have questions on this matter or need additional assistance, please contact csr@zilog.com.

Thank you for your continued interest in Zilog products and services.

Sincerely,

Alan Shaw
AShaw@littelfuse.com
VP of Operations MCU
Zilog: a Littelfuse Company



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RELIABILITY TEST DATA:	REJ/SS
WIRE PULL	0/10
BALL SHEAR	0/3
DIE SHEAR	0/1
EXTERNAL VISUAL	0/125
PRECONDITIONING (30°C, 60%RH, 192 HRS)	0/135
PRESSURE POT (121°C, 100%RH, 2 ATM, 168 HRS)	0/45
TEMPERATURE CYCLE (-65°C, 150°C, 500X)	0/45
Biased HAST, 96 HRS	0/42
HTS (150°C, 168 HRS)	0/77
ZILOG QUALIFICATION REPORT	21012621

Affected PN	PLATE 1	PKG/LD
Z8FMC16100QKSG	8FMC16AB	32LD QFN
Z8FMC16100QKEG	8FMC16AB	32LD QFN
Z8FMC08100QKSG	8FMC16AB	32LD QFN
Z8FMC08100QKEG	8FMC16AB	32LD QFN
Z8FMC04100QKSG	8FMC16AB	32LD QFN
Z8FMC04100QKEG	8FMC16AB	32LD QFN
Z8F1681QK024XK2247	8FMC16AB	32LD QFN
Z8F6481QK024XK2247	8FMC16AB	32LD QFN
Z8F6081QK024XK2247	8FMC16AB	32LD QFN
Z8F3281QK024XK2247	8FMC16AB	32LD QFN
Z8F1681QK024XK		32LD QFN
Z8F6081QK024XK	8F6482AC	32LD QFN
Z8F3281QK024XK	8F6482AC	32LD QFN
Z8F6481QK024XK	8F6482AC	32LD QFN
Z8F1624QK020XK		32LD QFN
Z8F3224QK020XK	8F3224AC	32LD QFN
Z8F3224QK020XK2258	8F3224AC	32LD QFN
ZDU0210QUX		32LD QFN